

Please amend the claims as follows. This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Claim 17 (currently amended): A wafer preparation module, comprising:
an enclosure containing wafer engaging rollers, the wafer engaging rollers being oriented at an angle, the angle configured to be between 0° to 90°, the wafer engaging rollers designed to spin a wafer at ~~an~~ the angle during preparation.

Claim 18 (original): A wafer preparation module as recited in claim 17, wherein the preparation includes one of rinsing, cleaning, drying, scrubbing, and megasonic fluid application.

Claim 19 (original): A wafer preparation module as recited in claim 17, further comprising:

at least one cleaner dispenser configured to apply a fluid to a surface of the wafer during at least part of the preparation.

Claim 20 (original): A wafer preparation module as recited in claim 17, further comprising:

a nozzle configured to apply a gas flow toward at least one of wafer engaging rollers.

Claim 21 (original): A wafer preparation module as recited in claim 17, further comprising:

a megasonic spray assembly for applying a megasonic spray to a surface of the wafer.